One-cell Li-ion Battery Protection IC with High-accuracy Overcurrent Detection

No.EA-617-220311

OVERVIEW

The R5619L is a one-cell Li- ion / polymer battery protection IC providing overcharge, overdischarge and charge / discharge overcurrent detections. Major features of this device include charge / discharge overcurrent detectors with high accuracy of ±1.00 mV.

KEY BENEFITS

- Lower-resistance of sense resistor by overcurrent detector with lower-voltage and high-accuracy: Achieving heat reduction on board
- Low consumption current and low standby current: achieving longer driving time with a battery of small capacity

KEY SPECIFICATIONS

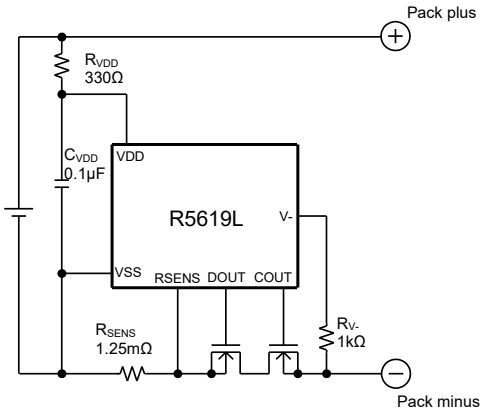
- Supply Current:
  Normal mode: Typ. 2 µA / Max. 4 µA
  Standby mode: Max.0.2 µA (V_{DET2}: Auto Release type) / Max.0.04 µA (V_{DET2}: Latch type)
- Detector Selectable Range and Accuracy
  Overcharge detection voltage (V_{DET1}): 4.2 V to 4.7 V, ±10 mV
  Overdischarge detection voltage (V_{DET2}): 2.0 V to 3.2 V, ±35 mV
  Discharge overcurrent detection voltage1 (V_{DET31}): 0.0030 V to 0.0300 V, ±1 mV
  Discharge overcurrent detection voltage2 (V_{DET32}): 0.010 V to 0.100 V, ±2 mV
  Charge overcurrent detection voltage (V_{DET4}): –0.0030 V to –0.0300 V, ±1 mV
  Short-circuit detection voltage (V_{SHORT1}): 0.020 V to 0.150 V, ±4 mV
- 0 V Battery Charging selectable: Permission / Inhibition
  0 V charging inhibition voltage: 1.000 V to 2.200 V
- Overcharge / Overdischarge Release Voltage Type selectable: Auto Release / Latch
  Discharge Overcurrent Release Voltage Type selectable: Auto Release1(V- = V_{DD} × 0.8V) / Latch
- Discharge Overcurrent Detection2 (V_{DET32}) selectable: Enable / Disable

PACKAGE

DFN1814-6B

1.4 x 1.8 x 0.4 [mm]

TYPICAL APPLICATION CIRCUIT



APPLICATIONS

- Smart Phone, Tablet PC
- Game, Hearing Aid

SELECTION GUIDE

Set Voltage, Delay Time and Optional Function are user selectable. Refer to *Product Code List* for major lineup.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R5619Lxxx$∗-TR	DFN1814-6B	5,000 pcs	Yes	Yes

xxx: Specify a code that combines the following set voltages. Refer to *Set Voltage Code in Product Code List* for major codes.

Overcharge Detection Voltage (V_{DET1}) ····· 4.2 V to 4.7 V in 5 mV step
Overcharge Release Voltage (V_{REL1}) ····· 4.0 V to 4.7 V in 5 mV step
(V_{DET1} – V_{REL1} = 0.400 V Max.)
Overdischarge Detection Voltage (V_{DET2}) ····· 2.0 V to 3.2 V in 50 mV step
Overdischarge Release Voltage (V_{REL2}) ..... 2.3 V to 3.2 V in 50 mV step
(V_{REL2} – V_{DET2} = 0.700 V Max.)
Discharge Overcurrent Detection Voltage 1 (V_{DET31}) (1) ···· 0.0030 V to 0.0300 V in 0.5 mV step
Discharge Overcurrent Detection Voltage 2 (V_{DET32}) (1) ···· 0.010 V to 0.100 V in 0.5 mV step
Short-circuit Detection Voltage (V_{SHORT1}) (1) ····· 0.020 V to 0.150 V in 1 mV step
Charge Overcurrent Detection Voltage (V_{DET4}) ····· –0.0030 V to –0.0300 V in 0.5mV step
0 V Battery Charging Inhibition Voltage (V_{NOCHG}) ····· 1.000 V to 2.200V in 0.1 V step

$: Specify a code that combines the following delay times. Refer to Set *Delay Time Code Table* for details.

Set Delay Time Code Table (Code Option (2))

Code	Delay Time [ms]									
	t_{VDET1}	t_{VREL1}	t_{VDET2}	t_{VREL2}	t_{VDET31}	t_{VDET32}	t_{VREL3}	t_{VDET4}	t_{VREL4}	t_{SHORT}
A	1024	1.5	128	1.05	3584	16	8.5	8.25	4	0.28
B	1024	1.5	128	1.05	3584	32	8.5	32.25	4	0.53
C	1024	1.5	128	1.05	3584	-	8.5	32.25	4	0.53
D	1024	1.5	128	1.05	3584	-	8.5	8.25	4	0.28
E	1024	1.5	64	1.05	128	-	8.5	32.25	4	0.28
F	1024	1.5	64	1.05	3584	16	8.5	16.25	4	0.28
G	1024	1.5	32	1.05	3584	16	8.5	16.25	4	0.28
H	1024	1.5	128	1.05	2048	16	8.5	8.25	4	0.28
V (3)	1024	1.5	64	1.05	128	-	8.5	64.25	4	0.28
W (3)	1024	1.5	64	1.05	64	-	8.5	32.25	4	0.28
Y (3)	1024	17	96	1.05	64	-	8.5	8.25	4	0.28

(1) When selecting each set voltage of V_{DET31}, V_{DET32} and V_{SHORT1}, keep from overlapping among them in consideration of their voltage accuracy. Especially, it is required that V_{SHORT1} be 7.5 mV higher than V_{DET31} and V_{DET32}.
(2) For more information on other code options, please contact our company's sales department.
(3) When selecting a code of V, W or Y, a combination with a function code is allowed the following codes only: VC, WC, YG, and YH.

*: Specify a code that combines the following functions. Refer to *Function Code Table* for details.

Function Code Table

Code	Release Condition			Discharge Overcurrent Detection2 (V_{DET32})	0 V Battery Charging
	Overcharge	Overdischarge	Discharge Overcurrent		
A	Auto Release	Auto Release	Auto Release1	Available	Permission
B	Auto Release	Auto Release	Auto Release1	Disable	Permission
C	Auto Release	Auto Release	Auto Release1	Disable	Inhibition
E	Latch	Latch	Latch	Available	Inhibition
F	Auto Release	Auto Release	Auto Release1	Available	Inhibition
G (1)	Latch	Latch	Auto Release1	Disable	Permission
H (1)	Latch	Latch	Auto Release1	Disable	Inhibition

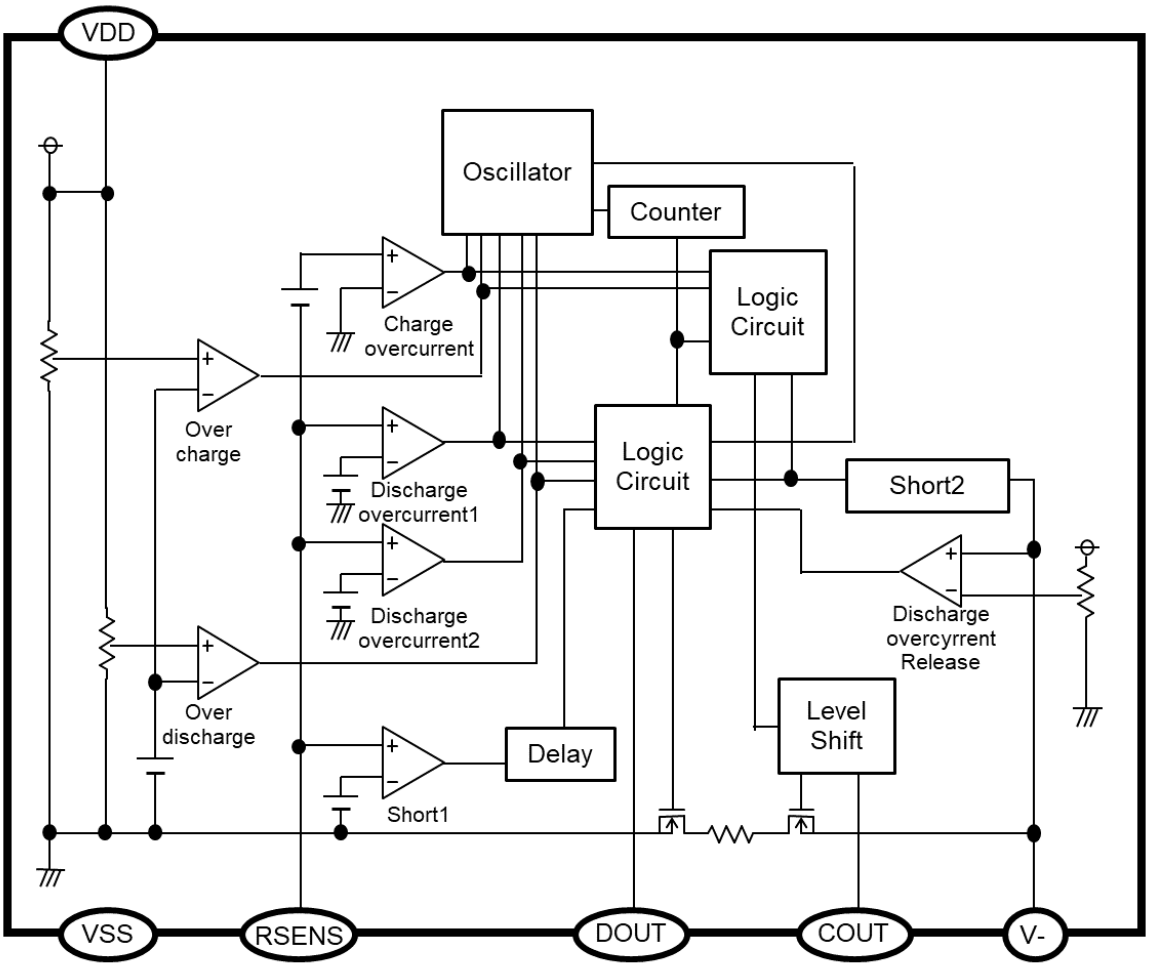
(1) When selecting a code of G or H, a combination with a delay time code is allowed the Y code only.

Product Code List

Product Name (Set Voltage Code [1])	Set Voltage [V]								
	V_{DET1}	V_{REL1}	V_{DET2}	V_{REL2}	V_{DET31}	V_{DET32}	V_{SHORT1}	V_{DET4}	V_{NOCHG}
R5619L**001**FA	4.580	4.380	2.35	2.55	0.0105	0.017	0.0420	–0.0150	-
R5619L**002**FA	4.600	4.400	2.10	2.30	0.0105	0.017	0.0420	–0.0180	-
R5619L**003**FA	4.580	4.380	2.35	2.55	0.0070	0.012	0.0280	–0.0120	-
R5619L**004**FA	4.600	4.400	2.10	2.30	0.0070	0.012	0.0280	–0.0140	-
R5619L**005**YG	4.525	-	2.50	-	0.0200	-	0.0750	–0.0250	-
R5619L**006**WC	4.595	4.395	2.50	2.90	0.0056	-	0.0225	–0.0113	1.1
R5619L**007**VC	4.615	4.405	2.30	2.50	0.0056	-	0.0225	–0.0113	1.2
R5619L**008**FF	4.580	4.380	2.35	2.55	0.0105	0.017	0.0420	–0.0150	1.2
R5619L**009**FF	4.600	4.400	2.10	2.30	0.0105	0.017	0.0420	–0.0180	1.2
R5619L**010**FF	4.580	4.380	2.35	2.55	0.0070	0.012	0.0280	–0.0120	1.2
R5619L**011**FF	4.600	4.400	2.10	2.30	0.0070	0.012	0.0280	–0.0140	1.2
R5619L**012**WC	4.595	4.395	2.50	2.90	0.0056	-	0.0225	–0.0113	1.2
R5619L**013**CB	4.580	4.380	2.35	2.55	0.0300	-	0.0375	–0.0150	-
R5619L**014**DC	4.580	4.380	2.35	2.55	0.0300	-	0.0390	–0.0150	1.2
R5619L**016**GE	4.580	-	2.35	-	0.0105	0.017	0.0420	–0.0150	1.2
R5619L**018**YH	4.525	-	2.50	-	0.0200	-	0.0750	–0.0250	1.2
R5619L**019**FF	4.580	4.380	2.35	2.55	0.0070	0.012	0.0280	–0.0150	1.2
R5619L**020**FF	4.600	4.400	2.10	2.30	0.0070	0.012	0.0280	–0.0180	1.2
R5619L**021**FF	4.580	4.380	2.35	2.55	0.0070	0.012	0.0280	–0.0180	1.2
R5619L**022**FF	4.600	4.400	2.10	2.30	0.0070	0.012	0.0280	–0.0200	1.2

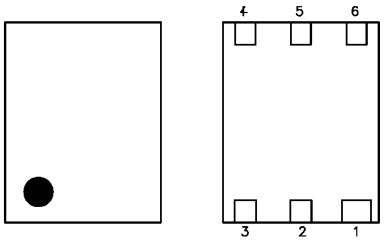
[1] Indicated with the numbers in bold type.

BLOCK DIAGRAM



R5619L Block Diagram

PIN DESCRIPTION



R5619L (DFN1814-6B) Pin Configuration

R5619L Pin Description

Pin No	Symbol	Pin Description
1	V-	Charge negative input pin
2	COUT	Charge detection output pin, CMOS output
3	DOUT	Discharge detection output pin, CMOS output
4	VSS	Ground pin for the IC
5	VDD	Power supply pin, the substrate level of the IC
6	RSENS	Overcurrent detection input pin

ABSOLUTE MAXIMUM RATINGS

(Ta = 25°C, V_{SS} = 0V)

Symbol	Parameter	Rating	Unit
V_{DD}	Supply voltage	–0.3 to 12	V
V-	V- pin input voltage	V_{DD} – 30 to V_{DD} + 0.3	V
V_{RSENS}	RSENS pin input voltage	V_{SS} – 0.3 to V_{DD} + 0.3	V
V_{COUT}	COUT pin output voltage	V_{DD} – 30 to V_{DD} + 0.3	V
V_{DOUT}	DOUT pin output voltage	V_{SS} – 0.3 to V_{DD} + 0.3	V
P_D	Power Dissipation	150	mW
Tj	Junction Temperature Range	–40 to 125	°C
Tstg	Storage Temperature Range	–55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the lifetime and safety for both device and system using the device in the field.
The functional operations at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITION

Symbol	Parameter	Rating	Unit
V_{DD}	Operating Input Voltage	1.5 to 5.0	V
Ta	Operating Temperature Range	–40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

ELECTRICAL CHARACTERISTICS

R5619Lxxxxx Electrical Characteristics **(Ta = 25°C)**

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Unit	Circuit (1)
V_{STCHG}	Minimum charging voltage for 0 V battery charger (2)	V_{DD} – V-, V_{DD} – V_{SS} = 0 V				1.8	V	A
V_{NOCHG}	0 V-battery Charging Inhibition Voltage (3)	V_{DD} – V_{SS}, V_{DD} – V- =4 V		V_{NOCHG} – 0.1	V_{NOCHG}	V_{NOCHG} + 0.1	V	A
V_{DET1}	Overcharge detection voltage	R1 = 330Ω		V_{DET1} – 0.010	V_{DET1}	V_{DET1} + 0.010	V	B
V_{REL1}	Overcharge release voltage	R1 = 330Ω		V_{REL1} – 0.030	V_{REL1}	V_{REL1} + 0.030	V	B
t_{VDET1}	Overcharge detection delay time	V_{DD} = 3.6 V → V_{DET1} + 0.1 V		t_{VDET1} × 0.80	t_{VDET1}	t_{VDET1} × 1.20	s	C
t_{VREL1}	Overcharge release delay time	V_{DD} = 4.8 V → V_{REL1} – 0.1 V, V- = 0 V to 1 V (Latch type only)	t_{VREL1} = 1.5 ms	0.7	1.5	2.5	ms	C
			t_{VREL1} = 17 ms	13.6	17	20.4		
V_{DET2}	Overdischarge detection voltage	Detect falling edge of supply voltage		V_{DET2} – 0.035	V_{DET2}	V_{DET2} + 0.035	V	D
V_{REL2}	Overdischarge release voltage	Detect rising edge of supply voltage		V_{REL2} – 0.070	V_{REL2}	V_{REL2} + 0.070	V	E
t_{VDET2}	Overdischarge detection delay time	V_{DD} = V_{DET2} + 0.15 V → V_{DET2} – 0.1 V		t_{VDET2} × 0.80	t_{VDET2}	t_{VDET2} × 1.20	ms	D
t_{VREL2}	Overdischarge release delay time	V_{DD} = V_{DET2} – 0.2 V → V_{REL2} + 0.25 V		0.80	1.05	1.26	ms	E
V_{CHGDET}	Charger connection detection voltage	V_{DD} = V_{DET2} + 0.020 V, V_{RSENS} = 0 V		0.500	0.800	1.100	V	A
V_{DET31}	Discharge overcurrent detection voltage 1	V_{DD} = 3.6 V, V- = V_{RSENS}		V_{DET31} – 0.001	V_{DET31}	V_{DET31} + 0.001	V	F
t_{VDET31}	Discharge overcurrent 1 detection delay time	V_{DD} = 3.6 V, V_{RSENS} = 0V → V_{DET31} + 0.005V V- = V_{RSENS}		t_{VDET31} × 0.80	t_{VDET31}	t_{VDET31} × 1.20	ms	F
V_{DET32}	Discharge overcurrent detection voltage 2	V_{DD} = 3.6 V, V- = V_{RSENS}		V_{DET32} – 0.002	V_{DET32}	V_{DET32} + 0.002	V	F
t_{VDET32}	Discharge overcurrent 2 detection delay time	V_{DD} = 3.6 V, V_{RSENS} = 0 V → V_{DET32} + 0.005 V V- = V_{RSENS}		t_{VDET32} × 0.80	t_{VDET32}	t_{VDET32} × 1.20	ms	F

(1) Refer to *TEST CIRCUITS* for detail information.
(2) 0 V battery charging permission supported product only.
(3) 0 V battery charging inhibition supported product only.

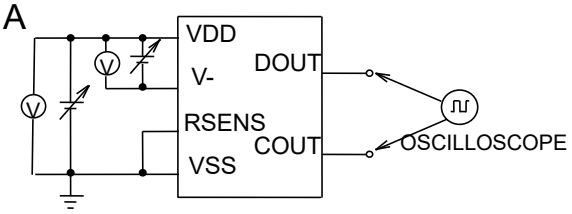
R5619Lxxxxx Electrical Characteristics (Continued) **(Ta = 25 °C)**

Symbol	Parameter	Conditions		Min.	Typ.	Max.	Unit	Circuit (1)
V_{SHORT1}	Short detection voltage1	Detect rising edge of RSENS pin voltage, V_{DD} = 3.6 V, V_{RSENS} = V-		V_{SHORT1} – 0.004	V_{SHORT1}	V_{SHORT1} + 0.004	V	F
t_{SHORT}	Short detection delay time (2)	V_{DD} = 3.6 V, V- = V_{RSENS}, V_{RSENS} = 0V → 1 V		210	280	384	µs	F
				371	530	689		
V_{SHORT2}	Short detection voltage2	Detect rising edge of V- pin voltage, V_{DD} = 3.6V, V_{RSENS} = 0V		V_{DD}×0.850 – 0.050	V_{DD} ×0.850	V_{DD}×0.850 + 0.050	V	F
V_{REL3}	Discharge overcurrent release voltage	V_{DD} = 3.6 V, V_{RSENS} = 0 V	Auto Release1	V_{DD}×0.800 – 0.050	V_{DD} × 0.800	V_{DD}×0.800 + 0.050	V	F
			Latch	V_{DD}×0.780 – 0.100	V_{DD} × 0.780	V_{DD}×0.780 + 0.100		
R_{SHORT}	Discharge overcurrent release resistance	Auto Release1: V_{DD} = 3.6 V, V- = 2.93V		5	10.0	15	kΩ	F
t_{VREL3}	Discharge overcurrent release delay time	V_{DD} = 3.6 V, V- = 3.6 V → 0 V V_{RSENS} = 0 V		6.8	8.5	10.2	ms	F
V_{DET4}	Charge overcurrent detection voltage	V_{DD} = 3.6 V, V- = V_{RSENS}		V_{DET4} – 0.001	V_{DET4}	V_{DET4} + 0.001	V	G
t_{VDET4}	Charge overcurrent detection delay time	V_{DD} = 3.6V, V_{RSENS} = 0V → –0.5V, V- = V_{RSENS}		t_{VDET4} × 0.80	t_{VDET4}	t_{VDET4} × 1.20	ms	G
V_{REL4}	Charge overcurrent release voltage	V_{DD} = 3.6 V, V_{RSENS} = 0 V		0.010	0.100	0.250	V	G
t_{VREL4}	Charge overcurrent release delay time	V_{DD} = 3.6 V, V- = –0.5 V → 1 V V- = V_{RSENS}		3.2	4	4.8	ms	G
V_{OL1}	COUT pin NMOS ON voltage	I_{OL} = 50 µA, V_{DD} = 4.80 V			0.4	0.5	V	H
V_{OH1}	COUT pin PMOS ON voltage	I_{OH} = -50 µA, V_{DD} = 3.9 V		3.4	3.7		V	I
V_{OL2}	DOUT pin NMOS ON voltage	I_{OL} = 50µA, V_{DD} = 1.9 V			0.2	0.5	V	J
V_{OH2}	DOUT pin PMOS ON voltage	I_{OH} = -50µA, V_{DD} = 3.9V		3.4	3.7		V	K
I_{DD}	Supply current	V_{DD} = 3.9 V, V- = 0 V			2.0	4.0	µA	L
$I_{STANDBY}$	Standby current	V_{DD}=1.9V	V_{DET2}: Auto Release			0.2	µA	L
			V_{DET2}: Latch			0.04		

(1) Refer to *TEST CIRCUITS* for detail information.
(2) Short release delay time 1 is the same value as t_{VREL3}.

Test Circuits

A



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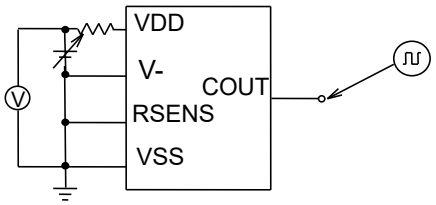

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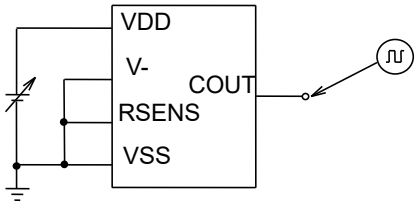

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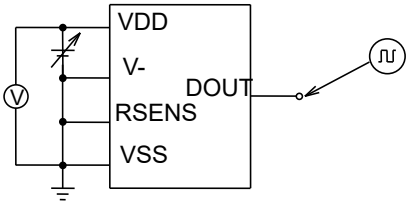

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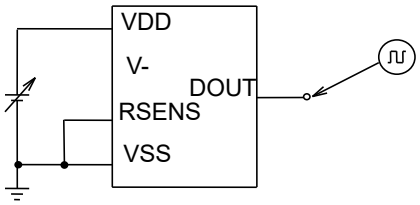

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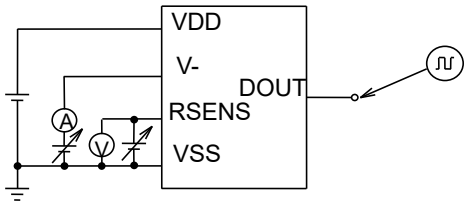

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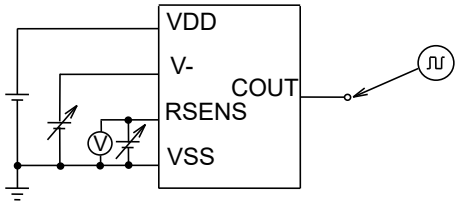

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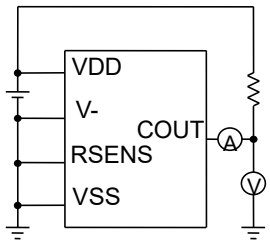

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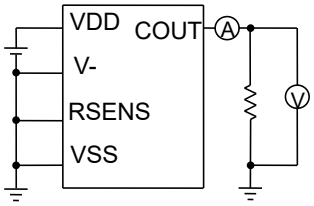

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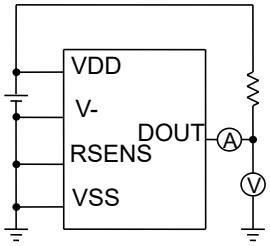

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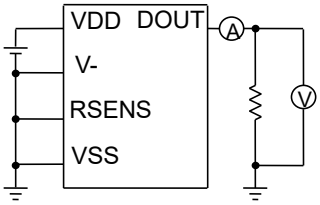

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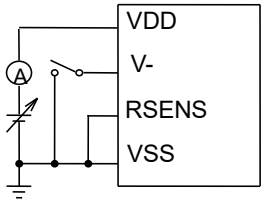


THEORY OF OPERATION

Overcharge Protection

When the overcharge detection delay time (t_{VDET1}) passes under the condition that the VDD pin voltage (V_{DD}) exceeds the overcharge detection voltage (V_{DET1}), this IC enters the overcharge state.
In this state, the COUT pin becomes Low, and the charge control FET is turned off to stop charging. The V- pin voltage (V-) increases by the Vf voltage (Vf) of the internal parasitic diode than the VSS pin voltage (V_{SS}) because the discharge current flows via the parasitic diode even when the charge control FET is off.
A release from the overcharge state must meet the following pin conditions and delay time according to the selected release type.

Type	Pin Conditions	Delay Time
Auto Release	V- < V_{REL4} and V_{DD} < V_{REL1} or V- > V_{REL4} and V_{DD} < V_{DET1}	t_{VREL1}
Latch	V- > V_{REL4} and V_{DD} < V_{DET1}	t_{VREL1}

Overdischarge Protection

When the overdischarge detection delay time (t_{VDET2}) passes under the condition that the VDD pin voltage (V_{DD}) falls below the overdischarge detection voltage (V_{DET2}), this IC enters the overdischarge state.
In this state, the DOUT pin becomes Low, and the discharge control FET is turned off to stop discharging. The V- pin voltage (V-) decreases by the Vf voltage (Vf) of the internal parasitic diode than the VSS pin voltage (V_{SS}) because the charge current flows via the parasitic diode even when the discharge control FET is off.
In addition, when V- is pulled up to V_{DD} level and exceeds the charger detection voltage (V_{CHGDET}), the IC enters the standby state. It results in reducing the standby current ($I_{STANDBY}$) to a minimum.
A release from the overdischarge state must meet the following pin conditions and delay time according to the selected release type.

Type	Pin Conditions	Delay Time
Auto Release	V- > V_{CHGDET} and V_{DD} > V_{REL2} or V- < V_{CHGDET} and V_{DD} > V_{DET2}	t_{VREL2}
Latch	V- < V_{CHGDET} and V_{DD} > V_{DET2}	t_{VREL2}

Discharge Overcurrent Protection

To monitor a discharge current, this IC measures a voltage difference of the sense resistor (R_{SENS}) connected between the RSENS and the VSS pins to detect the current value.
This IC has two levels of the discharge overcurrent detection voltage 1/2 (V_{DET31} / V_{DET32}). When the discharge overcurrent detection delay time (t_{VDET31}) passes under the condition that the discharge current, which is converted through R_{SENS} for current-to-voltage conversion, exceeds V_{DET31}, this IC enters the discharge overcurrent state. In a case where V_{DET32} is enabled, this IC enters the discharge overcurrent state when the discharge overcurrent detection delay time (t_{VDET32}) passes under the condition exceeding V_{DET32}.
In this state, the DOUT pin becomes Low, and the discharge control FET is turned off to shut off the discharge current.
A release from the discharge overcurrent state must meet the following pin condition and delay time according to the selected release type.

Type	Pin Condition	Delay Time	Remarks
Auto Release	V- < V_{REL3}	t_{VREL3}	V- is pulled down to the VSS level inside the IC. Note1
Latch	V- < V_{REL3}	t_{VREL3}	V- is pulled up to the VDD level inside the IC. Note2

Note1: It is possible to release the abnormal condition of the load connected to the battery pack. When the discharge overcurrent release delay time (t_{VREL3}) passes under the condition V- falls below V_{REL3}, this IC releases from the discharge overcurrent state. V- can be expressed by the following equation.

$$V\text{-} = V_{CELL} \times R_{SHORT} / (R_{SHORT} + R_{V\text{-}} + R_{LOAD})$$

V_{CELL} : Battery voltage
R_{SHORT} : Discharge overcurrent release resistance
$R_{V\text{-}}$: External resistor for V- pin
R_{LOAD} : Load resistance to a battery pack

Note2: When connecting a charger to pull V- down, this IC releases from the discharge overcurrent state.

Short-circuit Current Protection

To monitor a short-circuit current, this IC measures a voltage difference of the sense resistor (R_{SENS}) connected between the RSENS and the VSS pins to detect the current value. When the short-circuit current, which is converted through RSENS for current-to-voltage conversion, exceeds the short-circuit detection voltage (V_{SHORT}), this IC enters the short-circuit state. But it is possible for this IC to avoid its state when the short-circuit current falls below V_{SHORT} within the short-circuit detection delay time (t_{SHORT}).
In this state, the DOUT pin becomes Low, and the discharge control FET is turned off to shut off the short-circuit current.
A release from the short-circuit state must meet the same condition and delay time as the discharge overcurrent protection.

Charge Overcurrent Protection

To monitor a charge current, this IC measures a voltage difference of the sense resistor (R_{SENS}) connected between the RSENS and the VSS pins to detect the current value. When the charge overcurrent detection delay time (t_{VDET4}) passes under the condition that the charge current, which is converted through RSENS for current-to-voltage conversion, falls below the charge overcurrent detection voltage (V_{DET4}), this IC enters the charge overcurrent state.
In this state, the COUT pin becomes Low, and the charge control FET is turned off to shut off the charge current.
A release from the charge overcurrent state must meet the following pin condition and delay time according to the selected release type.

Type	Pin Condition	Delay Time	Remarks
Auto Release	V- > V_{REL4}	t_{VREL4}	V- is pulled up to the VDD level inside the IC. Note

Note: By disconnecting the charger, this IC releases from the charge overcurrent state.

0 V Battery Charging

This IC has the selectable charging function for the battery discharged to 0 V.

0 V Battery Charge Function “Permission”

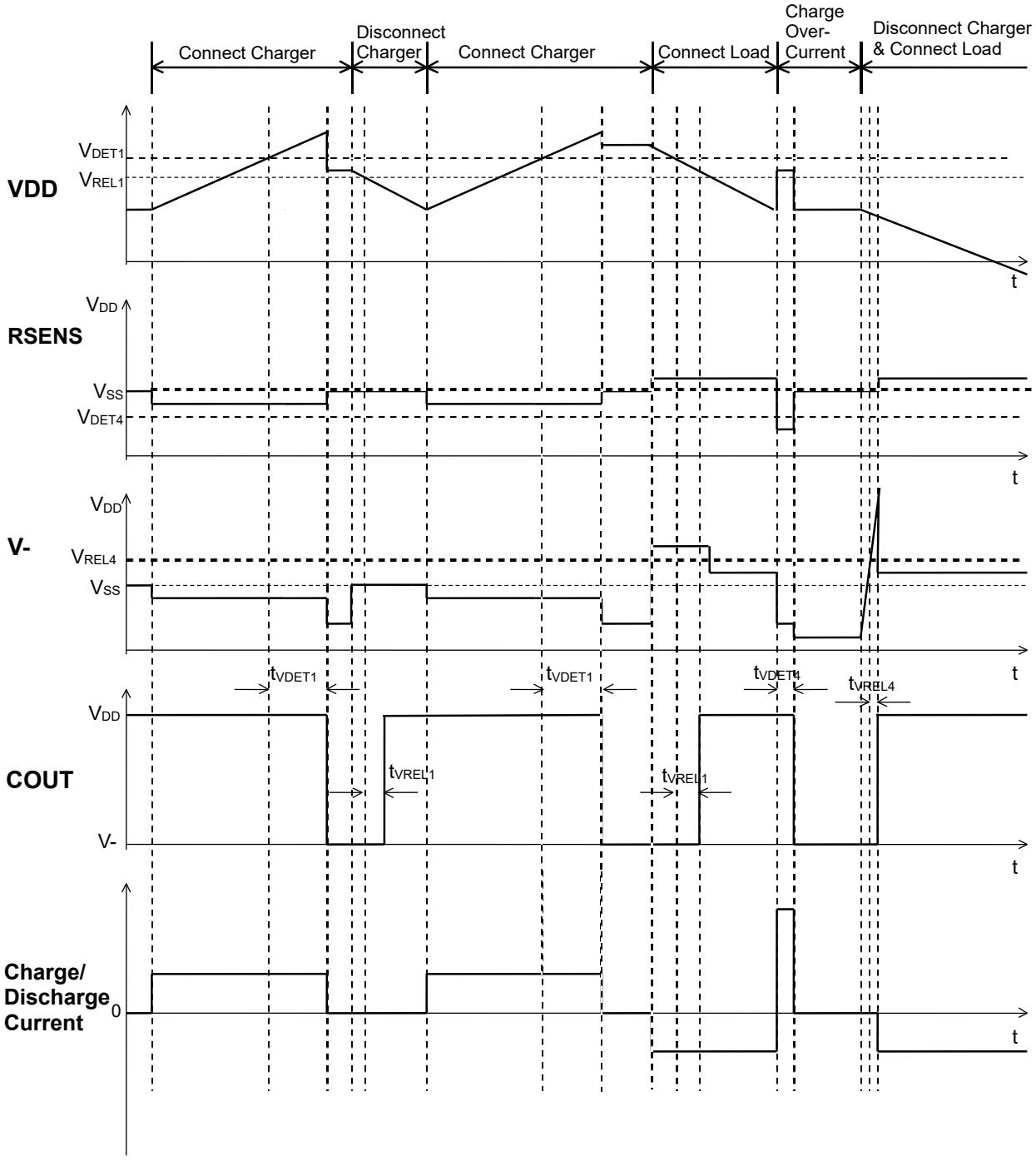
This function allows to charge to the 0 V battery by connecting the charger with the minimum charging voltage (V_{STCHG}) and more.

0 V Battery Charge Function “Inhibition”

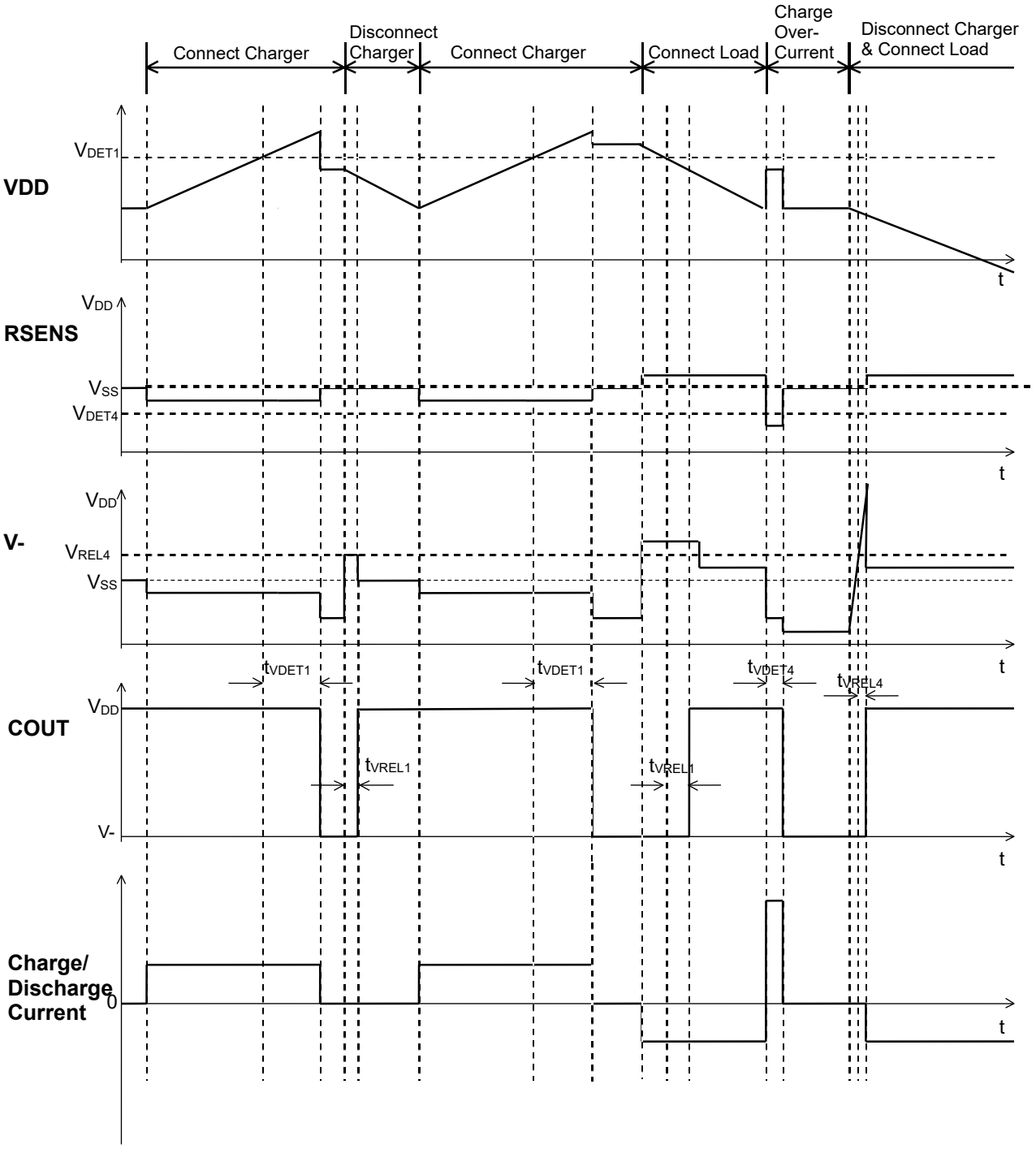
This function inhibits to charge to the battery with the 0 V-battery charging inhibition voltage (V_{NOCHG}) or less even if connecting the charger.

Timing Charts

Overcharge voltage and Overcharge current

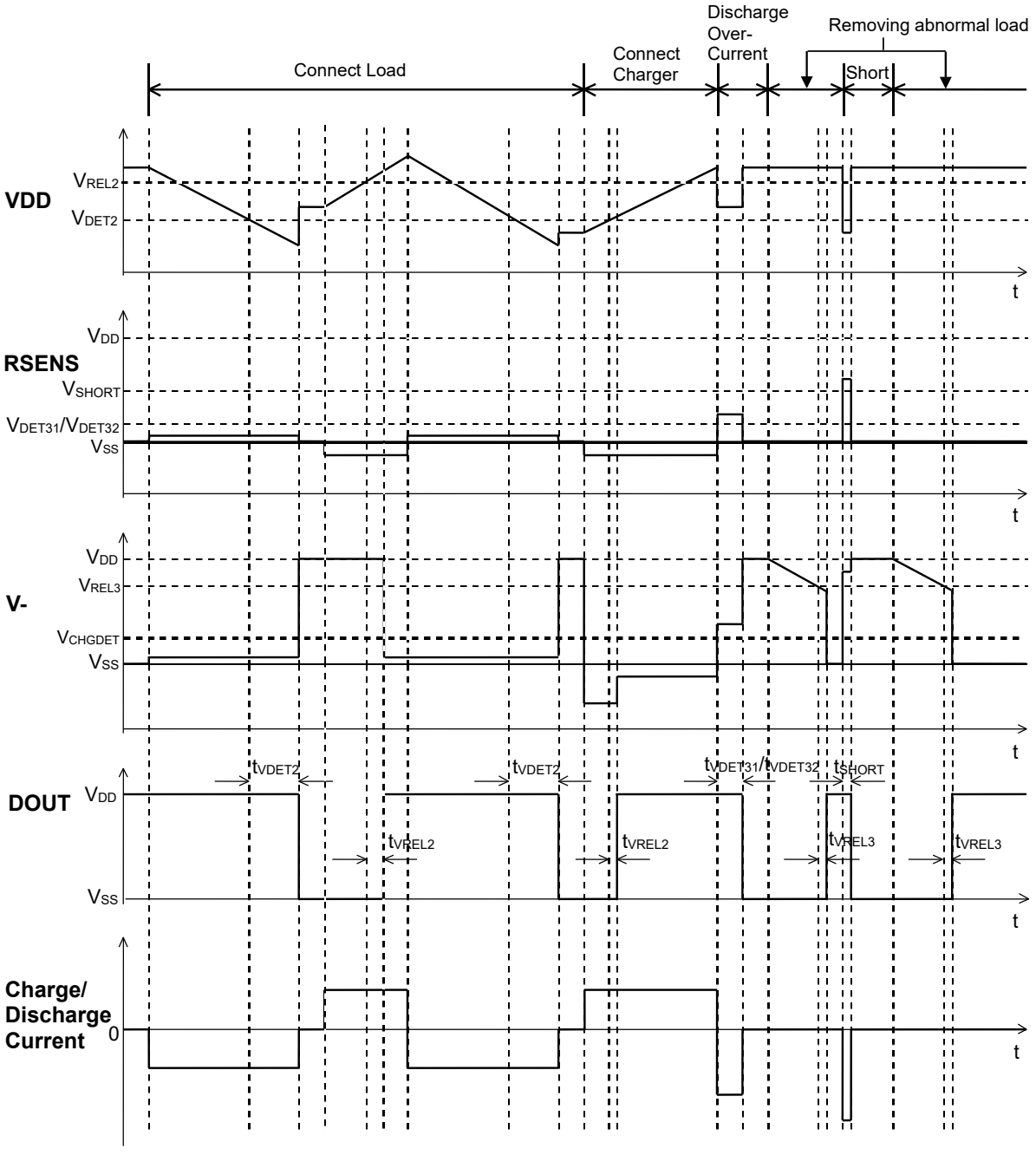


Overcharge (Auto Release type) Timing Diagram

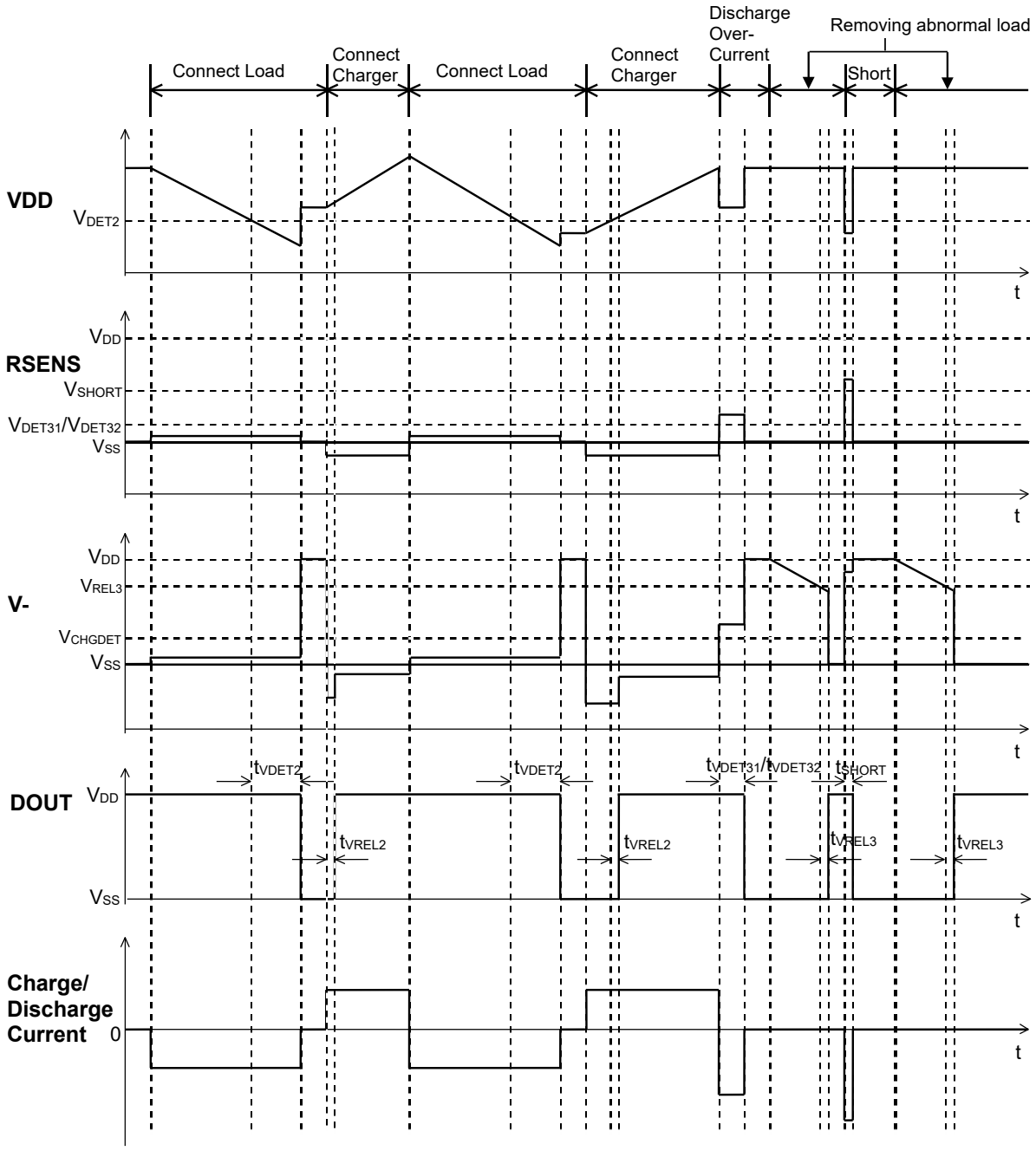


Overcharge (Latch type) Timing Diagram

Overdischarge / Discharge overcurrent and Short-circuit



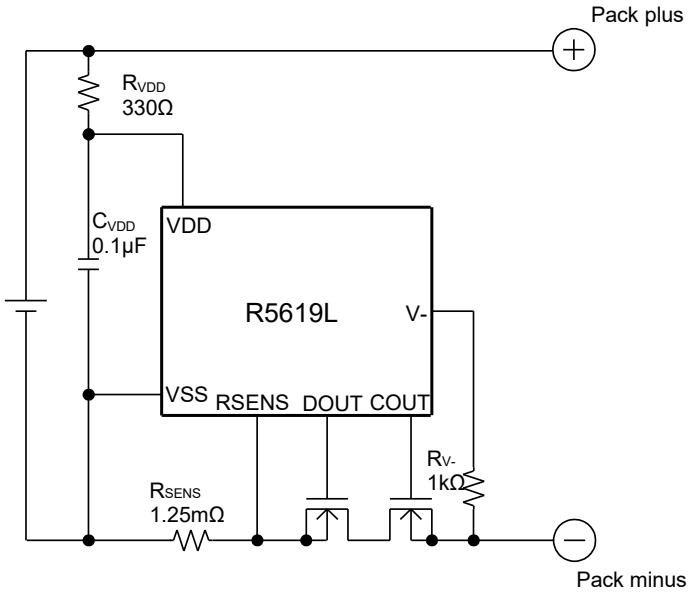
Overdischarge / Discharge Overcurrent (Auto Release type), Short-circuit Timing Diagram



Overdischarge / Discharge Overcurrent (Latch type), Short-circuit Timing Diagram

APPLICATION INFORMATION

Typical Application Circuit



R5619L Typical Application Circuit

External Components

Symbol	Min.	Typ.	Max.
Resistor			
R_{VDD} (1)		330Ω	1kΩ
R_{V-} (1)	−	1kΩ	1.3kΩ
R_{SENS}	−	1.25mΩ	20mΩ
Capacitor			
C_{VDD}	0.01µF	0.1µF	1µF

(1) The total resistance of R_{VDD} and R_V must be 1kΩ or more.

Technical Notes on External Components

- The voltage fluctuation is stabilized with R_{VDD} and C_{VDD}. If a R_{VDD} is too large, the detection voltage rises by the conduction current at detection. To stabilize the operation, it is recommended to use a resistor of 1kΩ or less for R_{VDD} and a capacitor of 0.01 μF to 1.0 μF for C_{VDD}.

- R_{VDD} and R_{V-} serve as a current limit resistor when the battery pack is charged with reversed polarity, or a voltage of the connected charger is more than the absolute maximum rating. When using a small resistor for R_{VDD} and R_{V-}, the device's power dissipation might be exceeded. Therefore, a total of R_{VDD} and R_{V-} must be 1kΩ or more. When using a large resistor for R_{V-}, the charger might not be released by re-connecting to the battery pack after the overdischarge detection. Therefore, R_{V-} must be 1.3 kΩ or less. Production variation and temperature properties are included in the value. R_{SENS} is a resistor for sensing an overcurrent. If the resistance value is too large, power loss becomes also large. By the overcurrent, if the R_{SENS} is not appropriate, the power loss may be beyond the power dissipation of R_{SENS}. Choose an appropriate R_{SENS} according to the cell specification.

- The typical application circuit diagrams are just examples. This circuit performance largely depends on the PCB layout and external components. In the actual application, fully evaluation is necessary.

- If the positive terminal and the negative terminal of the battery pack are short even though the device has the short protection circuit, a large current may flow through the FET during the short detection delay time. Therefore, select an appropriate FET with large enough current capacitance to endure the large current during the delay time.

Selection of External Sense Resistor and MOSFET

Short mode is detected by the current base or the relation between V_{DD} at short and total on resistance of external MOSFETs for C_{OUT} and D_{OUT}. If short must be detected by the current base determined by V_{SHORT1}, V_{SHORT2}, and R_{SENS}, the next formula must be true, otherwise, the short current limit becomes (V_{SHORT2}) / (R_{SENS} + R_{SS} (on)).

$$\frac{V_{SHORT2}}{R_{SENS}+Rss(on)} \geq \frac{V_{SHORT1}}{R_{SENS}}$$

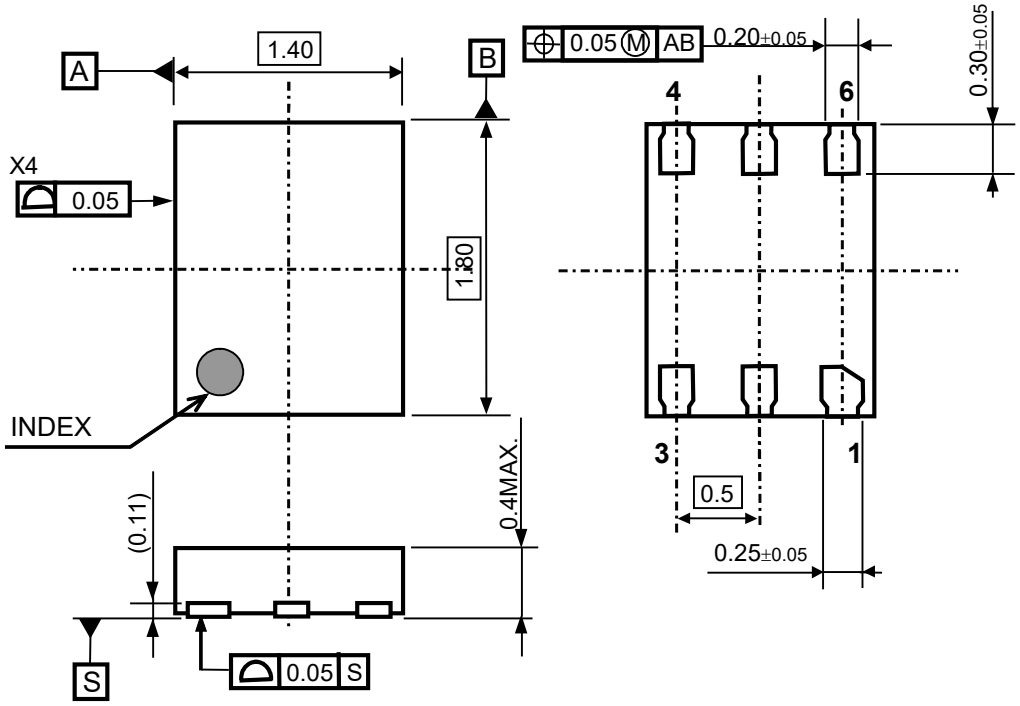
V_{SHORT1} = Threshold value of detecting short circuit using R_{SENS} terminal [V]
V_{SHORT2} =Threshold value of detecting short circuit using V- terminal [V]
R_{SENS}: = External current sense resistance [Ω]
R_{SS} (on) = external MOSFETs' total ON resistance [Ω]

In the short mode, a short current is determined by the relation between R_{SENS} and V_{SHORT} value.

TECHNICAL NOTES

A peripheral component or the device mounted on PCB should not exceed a rated voltage, a rated current or a rated power. When designing a peripheral circuit, please be fully aware of the following points.

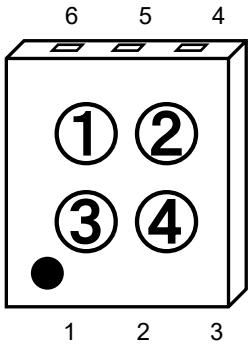
- Please evaluate the product at the PCB level before use, as some symptoms may remain that cannot be confirmed by the evaluation at the IC level.
- When using any coating or underfill to improve moisture resistance or joining strength, evaluate them adequately before using. In certain materials or coating conditions, corrosion by contained constituents, current leakage by moisture absorption, crack and delamination by physical stress can happen. If the curing temperature of the coating material or underfill material exceeds the absolute maximum rating, the electrical characteristics of this product may change.
- When performing X-ray inspection in mass production process and evaluation build stage such as the product functions and characteristics confirmation, please confirm X-ray irradiation does not exceed 1.5Gy (absorbed dose for air).



DFN1814-6B Package Dimensions (Unit: mm)

①②: Product Code ··· Refer to *Part Marking List*

③④: Lot Number ··· Alphanumeric Serial Number



R5619L (DFN1814-6B) Part Markings

NOTICE
There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or distributor before attempting to use AOI.

R5619LPart Marking List

Product Name	①	②
R5619L001FA	2	A
R5619L002FA	2	B
R5619L003FA	2	C
R5619L004FA	2	D
R5619L005YG	2	E
R5619L006WC	2	P
R5619L007VC	2	F
R5619L008FF	2	G
R5619L009FF	2	H
R5619L010FF	2	J
R5619L011FF	2	K
R5619L012WC	2	L
R5619L013CB	2	R
R5619L014DC	2	S
R5619L016GE	2	T

Product Name	①	②
R5619L018YH	2	U
R5619L019FF	2	M
R5619L020FF	2	N
R5619L021FF	2	V
R5619L022FF	2	W

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6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
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8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
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10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.
11. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.

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